



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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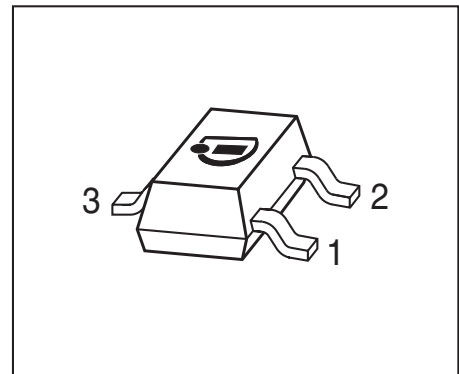
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**NPN Silicon RF Transistor**

- For amplifier and oscillator applications in TV-tuners
- Pb-free (RoHS compliant) package



**ESD (Electrostatic discharge)** sensitive device, observe handling precaution!

Type	Marking	Pin Configuration			Package
BF517	LRs	1 = B	2 = E	3 = C	SOT23

**Maximum Ratings** at  $T_A = 25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CEO}$	15	V
Collector-base voltage	$V_{CBO}$	25	
Emitter-base voltage	$V_{EBO}$	2.5	
Collector current	$I_C$	25	mA
Peak collector current	$I_{CM}$	50	
Total power dissipation $T_S \leq 55\text{ °C}$	$P_{tot}$	280	mW
Junction temperature	$T_J$	150	°C
Ambient temperature	$T_A$	-65 ... 150	
Storage temperature	$T_{Stg}$	-65 ... 150	

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup>	$R_{thJS}$	$\leq 340$	K/W

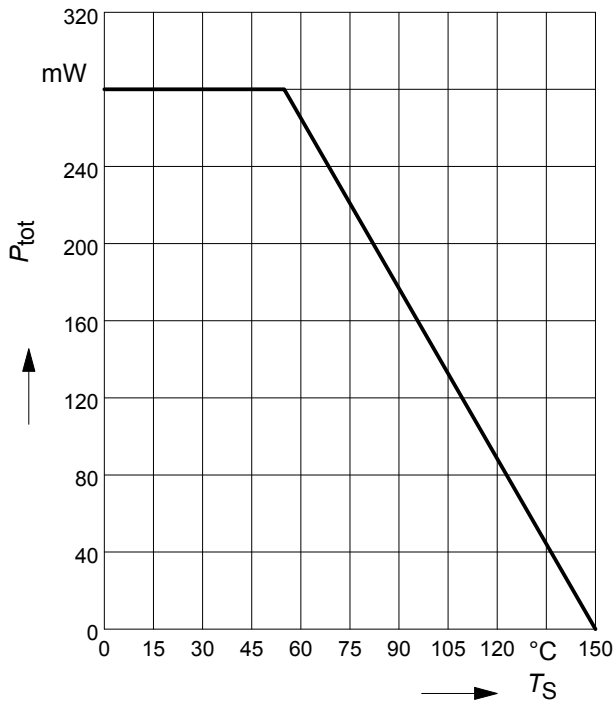
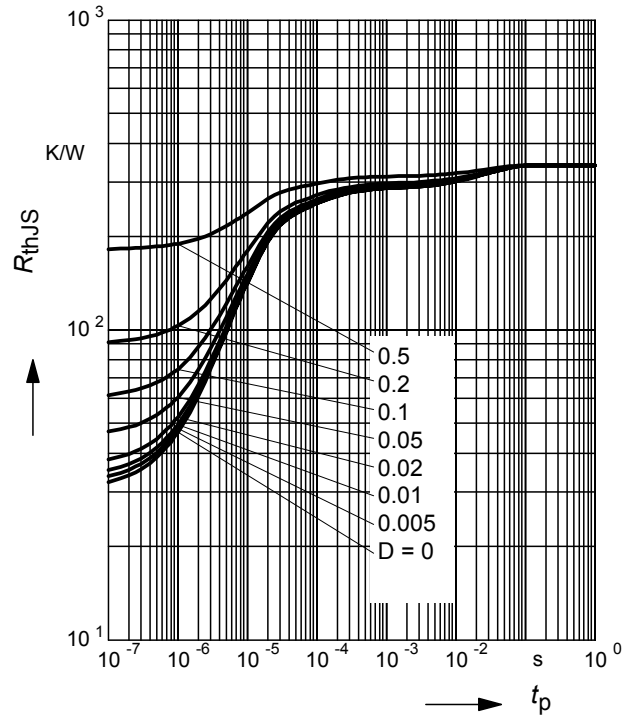
<sup>1)</sup>For calculation of  $R_{thJA}$  please refer to Application Note AN077 (Thermal Resistance Calculation)

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

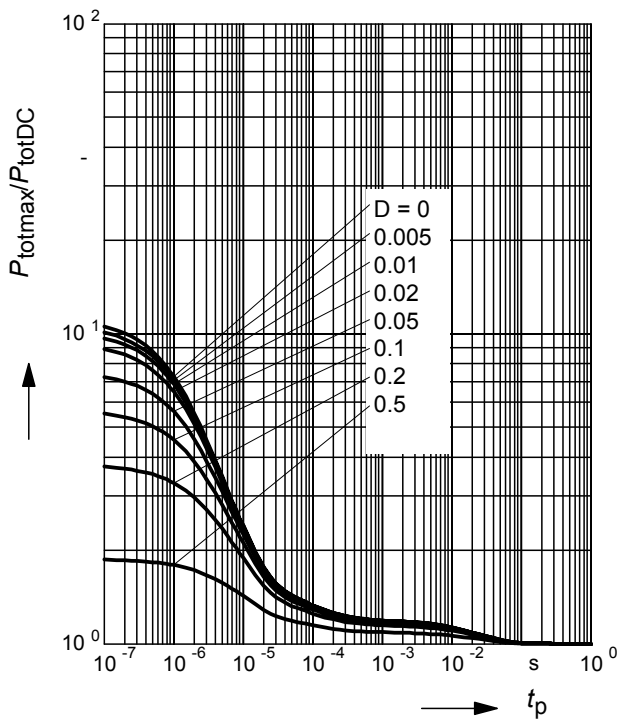
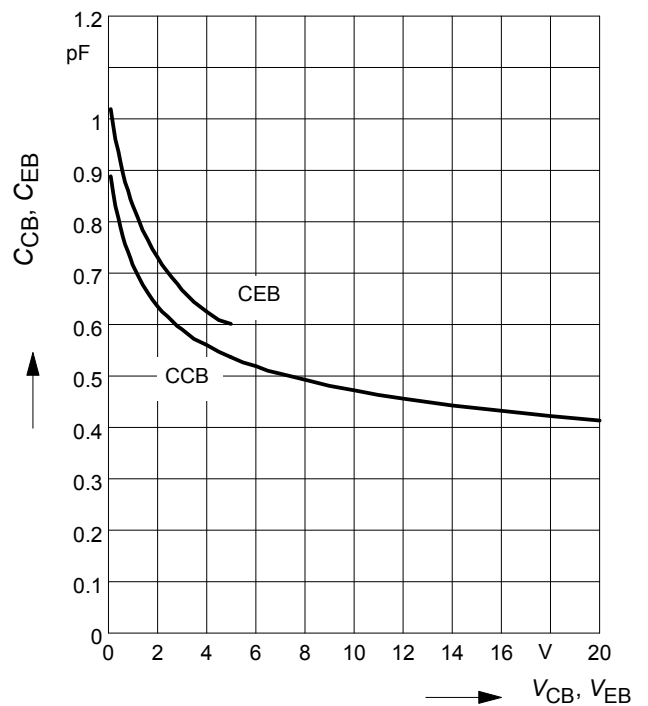
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Collector-emitter breakdown voltage $I_C = 1 \text{ mA}, I_B = 0$	$V_{(BR)CEO}$	15	-	-	V
Collector-base cutoff current $V_{CB} = 10 \text{ V}, I_E = 0$ $V_{CB} = 25 \text{ V}, I_E = 0$	$I_{CBO}$	-	-	0.05 10	$\mu\text{A}$
Emitter-base cutoff current $V_{EB} = 2.5 \text{ V}, I_C = 0$	$I_{EBO}$	-	-	100	nA
DC current gain $I_C = 2 \text{ mA}, V_{CE} = 1 \text{ V}, \text{ pulse measured}$ $I_C = 25 \text{ mA}, V_{CE} = 1 \text{ V}, \text{ pulse measured}$	$h_{FE}$	40 20	- 70	150 -	-
Collector-emitter saturation voltage $I_C = 10 \text{ mA}, I_B = 1 \text{ mA}$	$V_{CEsat}$	-	0.1	0.4	V

**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>AC Characteristics (verified by random sampling)</b>					
Transition frequency $I_C = 2\text{ mA}$ , $V_{CE} = 5\text{ V}$ , $f = 200\text{ MHz}$ $I_C = 25\text{ mA}$ , $V_{CE} = 5\text{ V}$ , $f = 200\text{ MHz}$	$f_T$	1 1.3	1.4 2.5	- -	GHz
Collector-base capacitance $V_{CB} = 5\text{ V}$ , $f = 1\text{ MHz}$ , $V_{BE} = 0$ , emitter grounded	$C_{cb}$	-	0.55	0.8	pF
Collector emitter capacitance $V_{CE} = 5\text{ V}$ , $f = 1\text{ MHz}$ , $V_{BE} = 0$ , base grounded	$C_{ce}$	-	0.27	-	
Emitter-base capacitance $V_{EB} = 0.5\text{ V}$ , $f = 1\text{ MHz}$ , $V_{CB} = 0$ , collector grounded	$C_{eb}$	-	0.9	1.45	
Minimum noise figure $I_C = 2\text{ mA}$ , $V_{CE} = 5\text{ V}$ , $Z_S = 50\ \Omega$ , $f = 800\text{ MHz}$	$NF_{min}$	-	3.5	5	dB
Transducer gain $I_C = 20\text{ mA}$ , $V_{CE} = 5\text{ V}$ , $Z_S = Z_L = 50\ \Omega$ , $f = 500\text{ MHz}$	$ S_{21e} ^2$	-	13	-	dB
Third order intercept point at output $V_{CE} = 5\text{ V}$ , $I_C = 20\text{ mA}$ , $f = 800\text{ MHz}$ , $Z_S = Z_{Sopt}$ , $Z_L = Z_{Lopt}$	$IP_3$	-	21.5	-	dBm
1dB compression point $I_C = 20\text{ mA}$ , $V_{CE} = 5\text{ V}$ , $Z_S = Z_L = 50\ \Omega$ , $f = 800\text{ MHz}$	$P_{-1dB}$	-	10	-	-

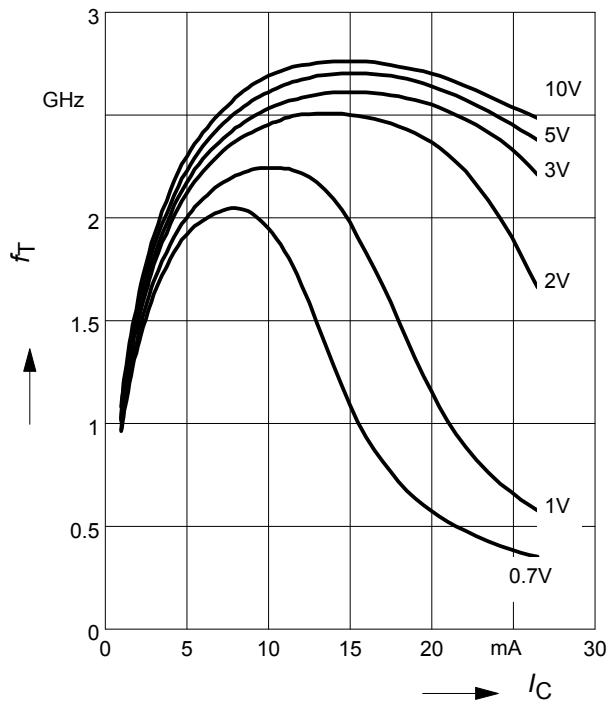
**Total power dissipation  $P_{\text{tot}} = f(T_S)$** 

**Permissible Pulse Load  $R_{\text{thJS}} = f(t_p)$** 

**Permissible Pulse Load**

$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

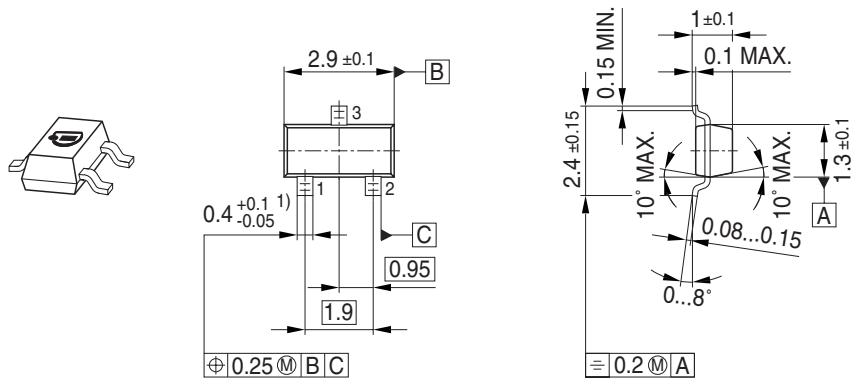

**Collector-base capacitance  $C_{\text{cb}} = f(V_{\text{CB}})$** 
**Emitter-base capacitance  $C_{\text{eb}} = f(V_{\text{EB}})$** 
 $f = 1 \text{ MHz}$ 


Transition frequency  $f_T = f(I_C)$

$V_{CE}$  = parameter

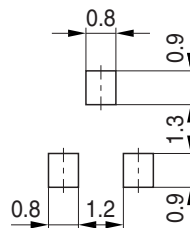


Package Outline

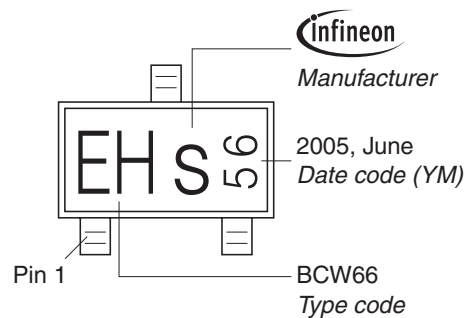


1) Lead width can be 0.6 max. in dambar area

Foot Print

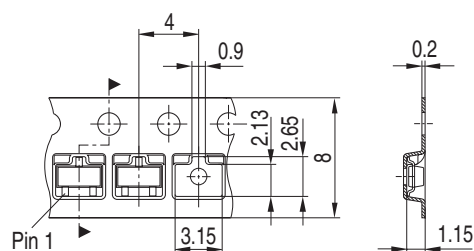


Marking Layout (Example)



Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



**Edition 2009-11-16**

**Published by  
Infineon Technologies AG  
81726 Munich, Germany**

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